



PK424 (v1.1) April 27, 2012

# 100% Material Declaration Data Sheet FTG256 XC3S200AN

**Average Weight: 0.7331 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die 1</b>					<b>0.008450</b>	<b>1.153%</b>
	Silicon (Si)	7440-21-3	100.00	Basis	0.008450	
<b>Silicon Die 2</b>					<b>0.002400</b>	<b>0.327%</b>
	Silicon (Si)	7440-21-3	100.00	Basis	0.002400	
<b>Die attach adhesive 1</b>					<b>0.001998</b>	<b>0.273%</b>
	Polymeric material	Proprietary	3.00	Main Material	0.000060	
	Di-ester resin	Proprietary	7.50	Main Material	0.000150	
	Functionalized ester	Proprietary	3.00	Main Material	0.000060	
	Silver (Ag)	7440-22-4	86.50	Main Material	0.001728	
<b>Die attach adhesive 2</b>					<b>0.000244</b>	<b>0.033%</b>
	Silicon dioxide	Proprietary	50.00	Main Material	0.000122	
	Di-ester resin	Proprietary	15.00	Main Material	0.000037	
	Epoxy resin	Proprietary	7.50	Main Material	0.000018	
	Polymeric material	Proprietary	7.50	Main Material	0.000018	
	Polymeric material	Proprietary	20.00	Main Material	0.000049	
<b>Mold Compound</b>					<b>0.382407</b>	<b>52.164%</b>
	Silica Fused	60676-86-0	85.20	Main Material	0.325811	
	Epoxy resin A	Trade Secret	3.00	Main Material	0.011472	
	Epoxy resin B	Trade Secret	3.00	Main Material	0.011472	
	Phenol resin A	Trade Secret	5.00	Main Material	0.019120	
	Phenol resin B	Trade Secret	1.50	Main Material	0.005736	
	Metal Hydroxide	Trade Secret	2.00	Main Material	0.007648	
	Carbon Black	1333-86-4	0.30	Main Material	0.001147	

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<b>Gold Wire 1.0 mil</b>					<b>0.009510</b>	<b>1.297%</b>
	Gold (Au)	7440-57-5	100.00	Main Material	0.009510	
<b>Gold Wire 1.1 mil</b>					<b>0.000360</b>	<b>0.049%</b>
	Gold (Au)	7440-57-5	100.00	Main Material	0.000360	
<b>Solder Ball</b>					<b>0.123760</b>	<b>16.882%</b>
	Tin (Sn)	7440-31-5	95.50	Main Material	0.118191	
	Silver (Ag)	7440-22-4	4.00	Main Material	0.004950	
	Copper (Cu)	7440-50-8	0.50	Main Material	0.000619	
<b>Substrate</b>					<b>0.203961</b>	<b>27.822%</b>
	Copper (Cu)	7440-50-8	33.37	Main Material	0.068062	
	Nickel (Ni)	7440-02-0	1.05	Main Material	0.002142	
	Gold (Au)	7440-57-5	0.28	Main Material	0.000571	
	Glass fiber	NA	13.20	Main Material	0.026923	
	Halogen FR	NA	5.80	Main Material	0.011830	
	BT (core)	NA	33.10	Main Material	0.067511	
	Solder mask	NA	13.20	Main Material	0.026923	

**Revision History**

The following table shows the revision history for this document.

Date	Version	Description of Revisions
08/17/10	1.0	Initial Xilinx release.
04/27/12	1.1	% of component update.

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